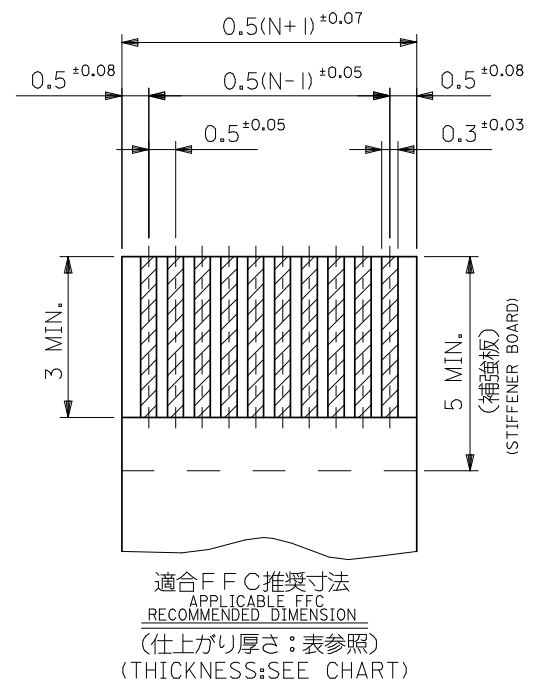
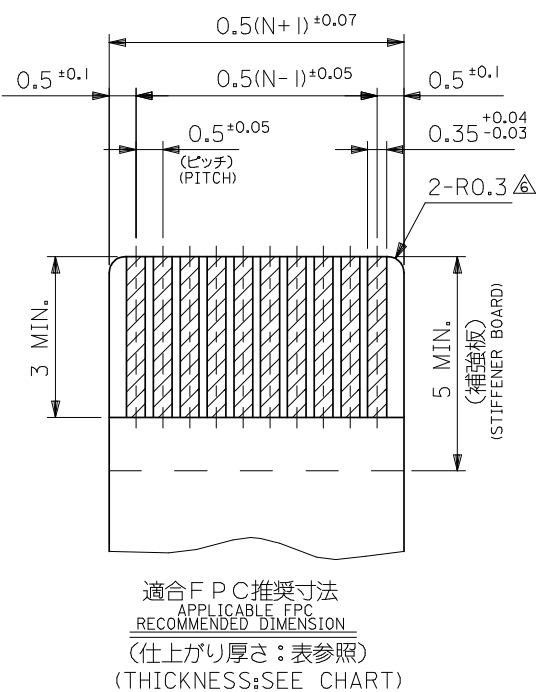
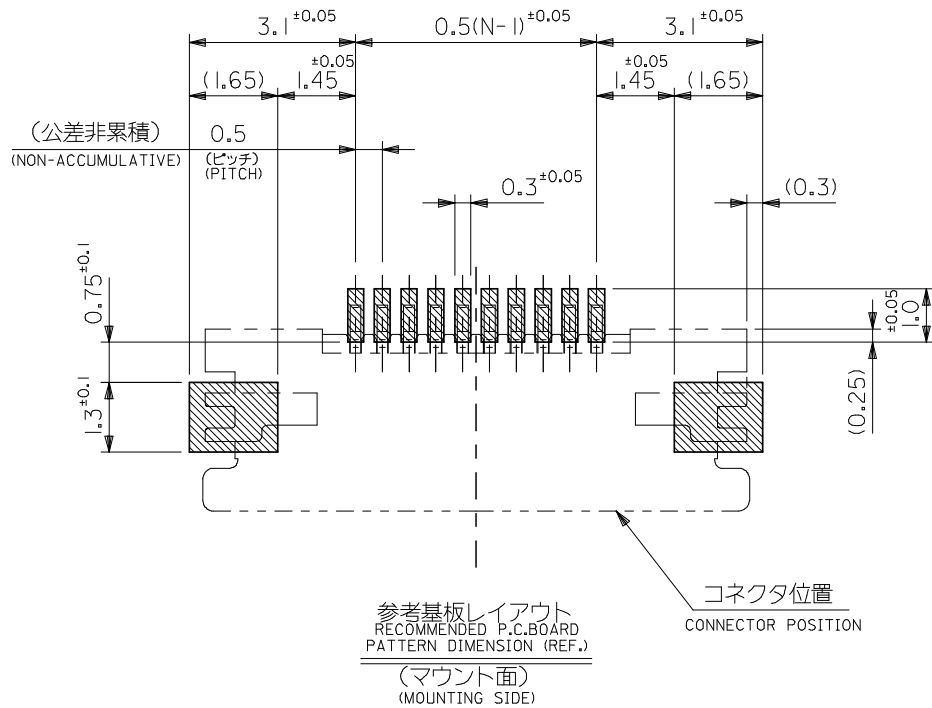


0.28±0.03	13.65	17.0	12.5	18.2	54548-2671	54548-2629	26	
	12.65	16.0	11.5	17.2	54548-2471	54548-2429	24	
	12.15	15.5	11.0	16.7	54548-2371	54548-2329	23	
	11.65	15.0	10.5	16.2	54548-2271	54548-2229	22	
	11.15	14.5	10.0	15.7	54548-2171	54548-2129	21	
	10.65	14.0	9.5	15.2	54548-2071	54548-2029	20	
	10.15	13.5	9.0	14.7	54548-1971	54548-1929	19	
	9.65	13.0	8.5	14.2	54548-1871	54548-1829	18	
	9.15	12.5	8.0	13.7	54548-1771	54548-1729	17	
	8.65	12.0	7.5	13.2	54548-1671	54548-1629	16	
	8.15	11.5	7.0	12.7	54548-1571	54548-1529	15	
	7.65	11.0	6.5	12.2	54548-1471	54548-1429	14	
	7.15	10.5	6.0	11.7	54548-1371	54548-1329	13	
0.3±0.03	6.65	10.0	5.5	11.2	54548-1271	54548-1229	12	
	6.15	9.5	5.0	10.7	54548-1171	54548-1129	11	
	5.65	9.0	4.5	10.2	54548-1071	54548-1029	10	
	5.15	8.5	4.0	9.7	54548-0971	54548-0929	9	
	4.65	8.0	3.5	9.2	54548-0871	54548-0829	8	
	4.15	7.5	3.0	8.7	54548-0771	54548-0729	7	
	3.65	7.0	2.5	8.2	54548-0671	54548-0629	6	
	3.15	6.5	2.0	7.7	54548-0571	54548-0529	5	
	2.65	6.0	1.5	7.2	54548-0471	54548-0429	4	
	FPC THICKNESS	D	C	B	A	EMBOSSED TAPE ORDER No. オータ-番号	製品番号 MATERIAL No.	極数 Ck+

REVISED EC NO: J2008-4048 DRW: MNABEI 2008/06/13 CHK: THARYAMA 2008/06/16 APPR: NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	DOCUMENT NO. SD-54548-039	SHEET NO. 1 OF 2
	ANGULAR ±3°		MATERIAL NO. SEE TABLE			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ:表参照)
(THICKNESS:SEE CHART)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ:表参照)
(THICKNESS:SEE CHART)

注記 NOTES

- I. 使用材料 MATERIAL
- ハウジング : LCP, UL94V-0
 - アクチュエータ : PPS, UL94V-0
 - ターミナル : リン青銅 (t=0.2)
 - メッキ : 接点部:金メッキ
 - テール部: 鍍メッキ
 - 金具 : リン青銅、鍍メッキ (t=0.2)

- △パターンはくり止め用金具
- △RO.3はFPC導体部にかからないこと
- 7.本製品は54548-**-21の鉛フリー(部分金メッキ)品である。
- 8. N: 極数 N: CIRCUIT.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35μmまたは50μmを推奨します。

ABOUT FPC/FFC
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC

RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE,ACTUATOR OF PART NO.54548-**-29 SHOULD BE LOCKED.
- △ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z に対し上方向 OMAX.、下方向 0.15MAX.とし
相互のバラツキ量は0.1MAX.とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION:0 MAX. , LOWER DIRECTION:0.15 MAX.
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.
- △偶数極に適用。
APPLY FOR EVEN CIRCUIT.

REVISED EC NO: J2008-4048 DRWN:WABEI CHKD:THARYAMA APPR:NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	MODEL No. 54548-**-29
	10 UNDER ±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	THIRD ANGLE PROJECTION	
	10 OVER 30 UNDER ±0.25	CHECKED BY KTOJO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-	
	30 OVER ±0.3	APPROVED BY MSASAO	DATE '04/02/10	MOLEX INCORPORATED	
	ANGULAR ±3	MATERIAL NO.	DOCUMENT NO.	SHEET NO. 2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 1		SD-54548-039		
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				